

Atty. Dkt. No. 039153-0683 (H1721)

**Amendments to the Specification:**

Please amend the specification as follows:

Please replace paragraph starting at page 9, paragraph number [0036] with the following rewritten paragraph:

[0036] Material 38 can be deposited in a conformal layer deposition process such as by plasma enhanced chemical vapor deposition or sputter deposition. Material 38 preferably has a thickness greater than or equal to one half the width associates with trenches 36 or 250-1000 Angstroms (Å) or more thick in a preferred embodiment Angstroms thick. For SiN, the deposition parameters of material 38 can be Silane (SiH<sub>4</sub>) + Ammonia (NH<sub>3</sub>) + Nitrogen (N<sub>2</sub>) using a pressure of 10-1000 MilliTorr, an rf power of 10-1000W, and a temperature of 100-~~500C~~ 500°C. Preferably, material 38 naturally compresses after deposition.